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AMENDMENTS TO THE CLAIMS

The following listing of the claims replaces all prior versions and listings of the claims in this application:

1-21. (Cancelled).

22. (Withdrawn) Electrical components, sheetlike insulating materials based on absorbent materials, and primed and unprimed substrates comprising at least one hot-melt resin, cured thermally and/or with actinic radiation, as claimed in claim 1.

23. (Withdrawn) An article obtained by the process of claim 11.

24. (Withdrawn) A process comprising impregnating a component or absorbent material with a hot melt resin according to claim 1.

25. (Withdrawn) The process of claim 24, wherein said component is an electronic component and said absorbent material is a sheetlike insulating material.

26. (Withdrawn) A process comprising coating a primed or unprimed substrate with a hot melt resin according to claim 1.

27. (Withdrawn) The process of claim 26, wherein said primed or unprimed substrate is a vehicle body part or packaging material.

28. (new) A process for the melt impregnation or melt coating of components, absorbent materials or primed and unprimed substrates comprising

- (i) melting a hot-melt resin,
- (ii) applying the resultant resin melt onto and into the components, absorbent materials or primed or unprimed substrates,
- (iii) curing the applied resin melt by heat and/or actinic radiation,

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wherein the hot-melt resin comprises

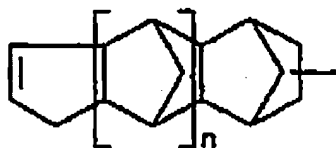
- A) at least one solid unsaturated polyester and
- B) at least one oligomeric and/or polymeric crosslinking agent which is copolymerizable with said polyester and which in respect of the oligomeric and/or polymeric main chain comprises at least one terminal and/or pendant isoprenyl group,

wherein at least one of the unsaturated polyesters (A) has at least one structural unit of the general formula I



(I)

and/or at least one structural unit of the general formula II



(II)

in which the index n is an integer from 1 to 10,

wherein component (A) is different than component (B).

29. (new) The process as claimed in claim 28, wherein the crosslinking agents (B) have at least two terminal and/or pendant isoprenyl groups.

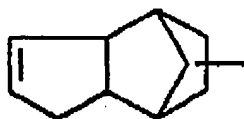
30. (new) The process as claimed in claim 28, wherein the oligomer and polymer main chains are formed by linear, branched and/or dendrimeric, saturated and/or unsaturated polyesters, polyester amides, and/or polyurethanes.

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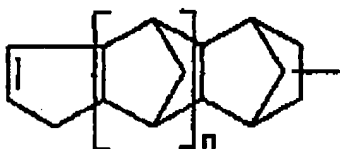
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31. (new) The process as claimed in claim 28, wherein at least one of the crosslinking agents (B) has at least one structural unit of the general formula I



(I)

and/or at least one structural unit of the general formula II



(II)

in which the index n is an integer from 1 to 10.

32. (new) The process as claimed in claim 28, wherein said hot-melt resin further comprises additives.

33. (new) The process as claimed in claim 32, wherein said hot-melt resin further comprises a photoinitiator that is bonded chemically to at least one of the unsaturated polyesters (A) and/or at least one of the crosslinking agents (B).

34. (new) The process as claimed in claim 28, wherein the application (ii) takes place by placing at least one shaped part comprising the hot-melt resin and adapted in its shape to the shape of the component, absorbent material or primed and unprimed substrate to be coated onto the component, absorbent material or primed and unprimed substrate, and melting the shaped part,
or by

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dipping, hot-dipping, dip-rolling, flooding, casting, vacuum impregnation, vacuum pressure impregnation or trickling.

35. (new) The process as claimed in claim 28, wherein the applied hot-melt resin is partially gelled (process step iv) before process step (iii).

36. (new) The process as claimed in claim 28, wherein the applied hot-melt resin in process step (iii) is cured by thermal curing by means of electricity, induction, hot fluids, especially hot gases, microwave radiation and/or IR radiation, especially near infrared (NIR) radiation.

37. (new) The process as claimed in claim 28, wherein the applied hot-melt resin in process step (iii) is cured by electromagnetic radiation and/or corpuscular radiation.